

C0603S222K1RACTU

Aliases (C0603S222K1RAC7867)

SMD Comm X7R FE, Ceramic, 2200 pF, 10%, 100 VDC, X7R, SMD, MLCC, FE-CAP, Floating Electrode, Temperature Stable, 0603



Click here for the 3D model.

Chip Size 0603 L 1.6mm +/-0.15mm W 0.8mm +/-0.15mm T 0.8mm +/-0.07mm S 0.7mm MIN B 0.35mm +/-0.15mm	Dimensions	
W 0.8mm +/-0.15mm T 0.8mm +/-0.07mm S 0.7mm MIN	Chip Size	0603
T 0.8mm +/-0.07mm S 0.7mm MIN	L	1.6mm +/-0.15mm
S 0.7mm MIN	W	0.8mm +/-0.15mm
	Т	0.8mm +/-0.07mm
B 0.35mm +/-0.15mm	S	0.7mm MIN
	В	0.35mm +/-0.15mm

Packaging Specifications	
Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

General Information	
Series	SMD Comm X7R FE
Style	SMD Chip
Description	SMD, MLCC, FE-CAP, Floating Electrode, Temperature Stable
Features	FE-CAP, Floating Electrode, Temperature Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	4.8 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	2200 pF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	100 VDC
Dielectric Withstanding Voltage	250 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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